

CLAIMS

1. A method of applying and curing a coating on opposed sides of a circuit board comprising the steps of:

positioning a circuit board (18) on a supporting tool (12);

providing a conformal coating material (22) which includes a moisture curing agent;

advancing the tool (12) to a dip coating tank (20) containing the conformal coating material (22);

immersing the circuit board to a predetermined position in the tank (20) so as to coat opposed sides of the circuit board (18) with the conformal coating material (22);

advancing the tool (12) to opposed ultraviolet lamps (38); and

curing the coating of conformal coating material on both sides of the circuit board (18) substantially simultaneously by means of the ultraviolet radiation emitted by the lamps (38).

2. A method according to Claim 1 comprising the step of:

providing a nitrogen blanket over the conformal coating material (22) in the dip coating tank (20) at a rate of substantially 148 to 167 cubic metres/hour.

3. Dip coating apparatus for applying and curing a coating on opposed sides of a circuit board comprising a

supporting tool (12) for supporting a circuit board; advancing means for advancing the tool between stations of the apparatus; a coating station (20) including a dip-coating tank (20) which in use holds a conformal coating for coating a predetermined portion of a circuit board; and a curing station (34, 36) including at least one pair of spaced apart opposed ultraviolet lamps (38) each including an associated shutter (40), the lamps being adapted in use substantially simultaneously to cure a coating on opposed sides of a circuit board.